Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	3 X 3 X 0.85 (1.74 X 1.45 EP)
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.92E-03	86.91	869100	27.57	275667
Thermosets	Epoxy & Phenol Resin	Proprietary	8.70E-04	12.78	127800	4.05	40536
Other inorganic materials	Carbon black	1333-86-4	2.11E-05	0.31	3100	0.10	983
Subtotal			6.81 E-03	100.00	1000000	31.72	317187

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.17 E-02	97.50	975000	54.68	546763
Copper & its alloys	Iron	7439-89-6	2.83 E-04	2.35	23500	1.32	13178
Copper & its alloys	Zinc	7440-66-6	1.44 E-05	0.12	1200	0.07	673
Copper & its alloys	Phosphorus	7723-14-0	3.61 E-06	0.03	300	0.02	168
Subtotal			1.20 E-02	100.00	1000000	56.08	560782

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.10 E-04	100.0	1000000	1.44	14439

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.50 E-04	100.0	1000000	1.63	16302

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.60 E-04	100.0	1000000	1.68	16768

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.17 E-03	100.0	1000000	5.45	54495

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.34 E-04	77.71	777100	1.56	15564
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.34 E-05	3.11	31100	0.06	623
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.34 E-05	3.11	31100	0.06	623
Other organic materials	Butyrolactone, gamma-	96-48-0	1.34 E-05	3.11	31100	0.06	623
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.34 E-05	3.11	31100	0.06	623
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.34 E-05	3.11	31100	0.06	623
Other organic materials	Organosilane	TS ref# 10001	1.34 E-05	3.11	31100	0.06	623
Other inorganic materials	Copper(II) oxide	1317-38-0	1.34 E-05	3.11	31100	0.06	623
Other organic materials	Epoxy resin modifier	TS ref# 10038	2.24 E-06	0.52	5200	0.01	104
Subtotal			4.30 E-04	100.0	1000000	2.00	20028

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.15 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.